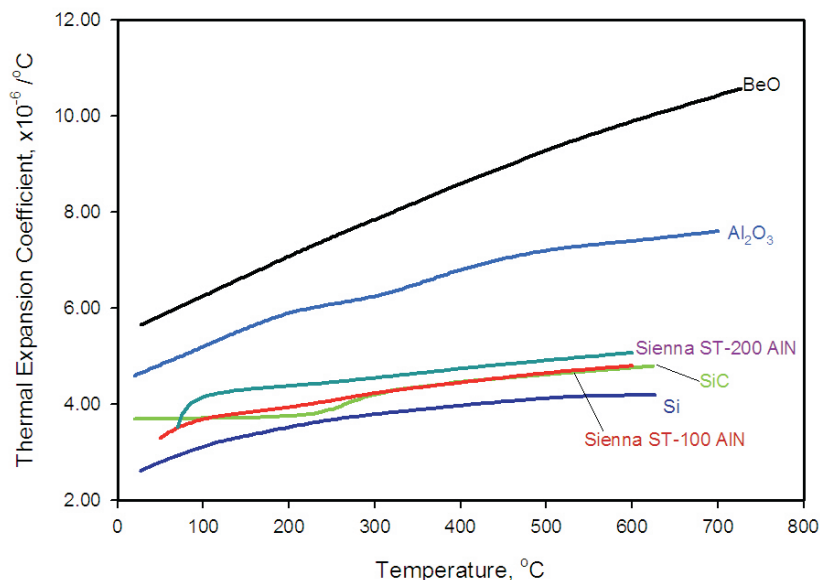


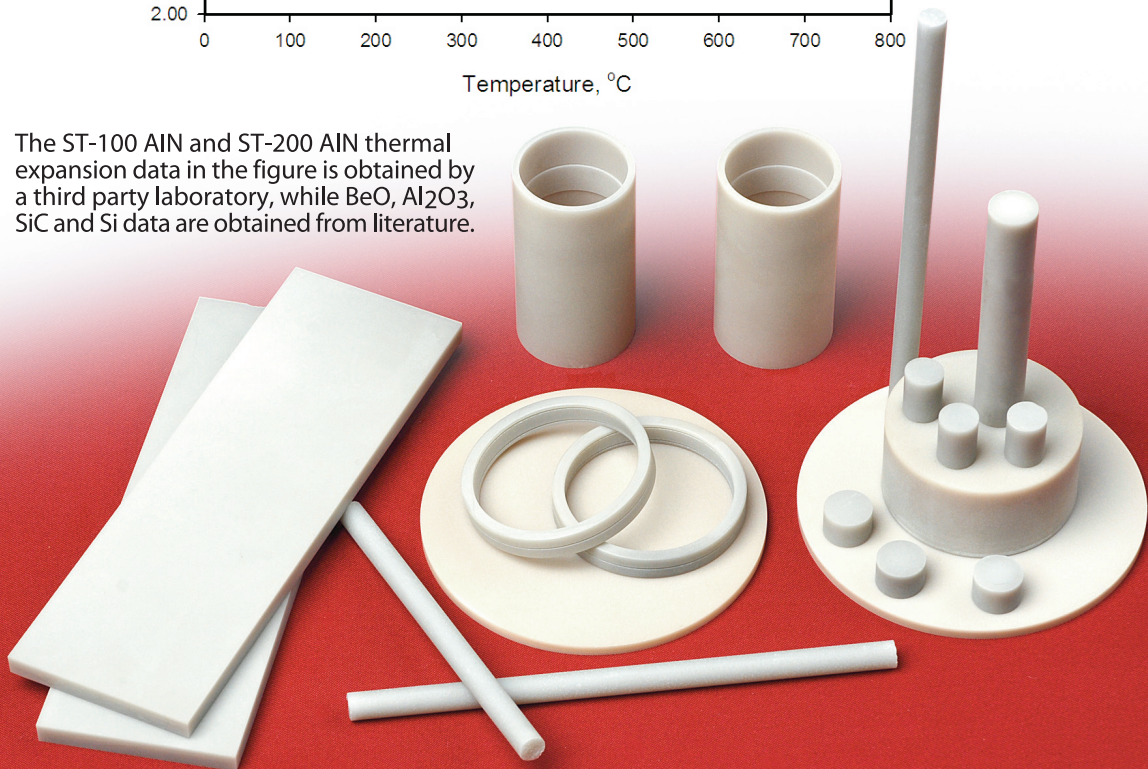
ST-100 and ST-200

THERMAL EXPANSION

Sienna ST-100 AlN and ST-200 AlN offer excellent thermal expansion match to Si, SiC, and GaN, and thus provide more reliable die attachment than alumina and beryllia, and allow mounting of larger devices in power electronics and microwave packaging applications.



The ST-100 AlN and ST-200 AlN thermal expansion data in the figure is obtained by a third party laboratory, while BeO, Al₂O₃, SiC and Si data are obtained from literature.



Sienna's technical team is ready to help you implement Aluminum Nitride in your next generation of products. Contact us for applications assistance and fast prototyping.

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